Goot XFC-200: Hot Air SMT Rework Tool

This is a hot air SMT rework tool with a built-in vacuum pickup. It allows easy mounting and removal of SMDs including QFPs and SQLs. When changing the nozzle it can be used for mounting and removing SMDs including discrete chips. This tool can be expended by installing a preheated (X-100) or rework base (X-Service, Super Service) for higher efficiency operation.

MODEL		XFC-200
Input Voltage		110-130V AC / 220-240V AC
Power Consumption		440-480 W (280Wh)
Heater Voltage & Wattage		110-120, 220-240 V AC 450 W
Air Flow Volume Meter		Standard
Vacuum Pickup		Standard
Mode		3 (HAND, PLACE, LIFT)
Temperature Profile		4 zones (Temperature and Time)
Profile Memory		6 (HAND x 2 , PLACE x 2 , Lift x 2)
Temperature Range		150°C ~ 450°C
Vacuum Pump System		Diaphragm system
Air Flow Volume		5 ~ 20 l/min
Dimensions	Hand piece	220 mm (w/o cord)
	Control unit	220 (L) x 1150 (W) x 220 (H) mm
Weight	Hand piece	200 g (w/o cord)
	Control unit	5.4 kg
Insulation Resistance 500VDC		Over 100 MOhm
Ground Resistance		Under 0.1 Ohm

Features

- Easy to use and ergonomic soldering station.
- Compatible with various types of nozzles (not included in the package).
- Air flow meter.
- Built-in vacuum tweezers.
- ESD safe.
- Compatible with Goot XFS-1 foot switch (not included in the package).

Technical specifications

Main Unit	
Power supply	220 V
Dimensions	227 × 107 × 177 mm
Weight	4,6 kg
Hot Air Gun	
Power consumption	400 to 450 W
Temperature range	150 to450 °C
Air flow speed	5 to 20 l/min (max)

Application

- Mounting and removal of SMDs (QFP, PLCC, SOL and BGA).

Contents

- Goot XFC-200 main unit
- Hot air gun with built-in vacuum twezers
- Power cord (1.1 m)
- User manual